

## EE BOM for Y500BT Wireless

Item	Part Number	Description	Qty
1	144-00133-601-041	Micro B USB Female Jack 5PIN SMD+DIP	1
2	144-00127-001-042	2.5mm Stereo Jack Black	1
3	140-00073-801-040	Dual LED Blue&Green SMD 1.6x0.8mm	1
4	140-00025-001-049	Water Clear Red Light LED (0603)	1
5	New part	DC-DC BUCK SGM6013-ADJ SOT23-5	1
8	144-00160-001-047	14-PIN FPC CONNECTOR 1226-14-01A-MCR SMD	2
9	142-00468-003-040	CTL-BT5221 BUTTONS PCB 2L FR4 T=1.0mm	1
10	134-00158-001-043	CE6209B30M Voltage Regulator 3V SOT-23-5	1
11	New part	ALPS SSAG230200 撥動開關	1
12	New part	ALPS SSAG330200 彈簧開關	1
13	122-00071-002-045	Side-Push Tact Switch 4.5x3.55mm SMD	2
14	128-00119-004-044	4.7uH±20% LQM18PN4R7MFRL INDUCTOR 0603	1
15	132-00097-801-047	ESD ESD5451N 6.8V 17.5pF	3
16	124-01106-016-042	10UF/10V MULTILAYER C.CAP 0402 X5R ±10%	6
17	124-01475-605-043	4.7uF/6.3V Multilayer CAP 0402 X5R ±10%	6
18	124-01104-014-046	100nF/6.3V CERAMIC CAP 0201 ±10% X5R	5
19	126-01000-004-046	0Ω(<0.05Ω) Thick Film Fixed Res 0402	2
20	124-01100-003-044	10pF/25V Multilayer C.CAP 0201 COG±0.5p	2
21	124-01180-004-049	18pF/25V CERAMIC CAP 0201 COG ±5%	1
22	124-01105-013-046	1.0UF/6.3V Multilayer CAP 0201 X5R ±20%	11
23	124-01105-605-045	1uF/25V Multilayer CAP 0402 X5R ±10%	8
24	124-01330-602-040	33pF/50V MULTILAYER CAP 0201 COG ±5%	9
25	124-01056-602-049	5.6±0.1pF 50V 0201 Cap GRM0335C1H	1
26	124-01068-602-044	6.8±0.1pF 50V 0201 Cap GRM0335C1H	1
27	128-00151-001-043	15nH ±5%(@ 500MHz) Chip Inductor 0201	6
28	126-01104-010-046	100KΩ Thick Film Fixed Res 0201 ±1%	1
29	126-01103-015-042	10KΩ Thick Film Fixed Res 0201 ±1%	8
30	126-01154-601-041	150KΩ Thick Film Fixed Res 0201 ±1%	1
31	126-01222-014-041	2.2KΩ Thick film fixed RES 0201 ±1%	1
32	126-01223-012-042	22kΩ Thick Film Fixed Res 0201 +/-5%	2
33	126-01304-005-040	300KΩ Thick Film Fixed Res 0201 ±1%	1
34	126-01331-010-046	330Ω Thick Film Fixed Res 0201 +/-5%	3
35	126-01474-007-040	470KΩ Thick Film Fixed Res 0201 ±1%	3
36	126-01471-008-042	470Ω Thick Film Fixed Res 0201 ±1%	3
37	126-01000-009-041	0Ω(<0.05Ω) Thick Film Fixed Res 0201	2
38	126-00005-001-045	237KΩ Thick Film Fixed Res 0402 ±1%	1
39	142-00552-001-044	CTL-BT5287 USB PCB 2L FR4 T=1.0mm	1
40	142-00552-002-043	CTL-BT5287 MAIN PCB 2L FR4 T=1.0mm	1
41	124-01104-016-044	100NF/50V MULTILAYER C.CAP(0402)X7R±10%	2
42	124-01106-014-044	10uF/25V CERAMIC CAP 0805 X5R ±10%	2
43	126-01222-007-041	2.2K OHM SOLID RESISTOR SMD (0402) ±5%	3
44	126-01391-005-046	390 OHM Thick Film Fixed Res 0402 +/-1%	3
45	142-00571-001-049	Y500 BT Touch PCB 2L FR4 T=1.0mm	1

BM2B-SBM. BM2B00000

SUNITEC ENTERPRISE CO., LTD

## 物料清单 (BOM)

发件部门	RD	发件时间	20170417	产品编号	BM20J00000		页码	1
项目名称	BM20J	产品类别	蓝牙模块	变更编码			版本	V0.1
层次号	物料编码	供应商元件编号	规格	封装	数量	装配位置	厂商	价格
1	SBM. BM20J0000		BM20J模块					
2	ELS. 201204U7001	CB2012T4R7M	Power Inductors 4.7UH $\pm$ 20% DCR=0.4R DCA=0.58A 2012 (TAIYO)	2012	1	L1	TAIYO	
3	EJO. 3D02D526000	7M26000056	3.2*2.5 26MHZ $\pm$ 10PPM 9PF TXC (7M26000056)	3.2*2.5	1	Y1	TXC	
4	ERS. 0402000R0J0	WR04X000PTL	0402 0R $\pm$ 5% (WALSIN)	402	2	R5, R2,	WALSIN	
5	ECS. 040204U7AM0	CL05A475MQ5NRNC	0402 4.7UF 6.3V $\pm$ 20% (SAMSUNG)	402	2	C16, C17	Samsung	
6	ECS. 0402001UDK0	CL05C105Z05NNNC	0402 1UF 16V $\pm$ 10% (Samsung)	402	9	C1, C3--C6, C9, C12--C13, C20	Samsung	
7	ECS. 04025P60GC1	CL05C5R6CB5NNNC	0402 5.6PF 50V $\pm$ 0.25PF	402	1	C7	SAMSUNG	
8	ECS. 04026P80GD0	CL05C6R8DB5NNNC	0402 6.8PF $\pm$ 0.5PF 50V (SAMSUNG)	402	1	C8	SAMSUNG	
9	ECS. 0603010UEK0	CL10A106MA8NRNC	0603 10UF 25V $\pm$ 20% X5R (SAMSUNG)	603	1	C2, C18	SAMSUNG	
10	ERS. 0402022K0F0		0402 22K $\pm$ 1% (国巨)		1	R1		
11	EPB. BM2B00001	BM2B_V0.1	BM2B_V0.1 (PCB丝印为"BM2B_V0.1") 四层板; 材质FR4; 厚度0.8mm; 沉金 14*19*0.8mm	14*19*0.8mm	1		博敏	
12	EIO. BES2000-B	BES2000-B	BES2000-B-bluetooth chipset_BGA-96L (5.9*5.5*1.18mm)	WLCSP 79-ball	1	BES2000-B	CSR	

制定	Darren	审核	Hiro	核准	Lixun
----	--------	----	------	----	-------